

S/N 10/826,508

In Response to Office Action mailed February 23, 2005

IN THE CLAIMS**Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 is amended.

Listing of Claims:

1. (Currently amended) A bonding ~~[[layer]]structure~~ for bonding resin ~~that is comprising a bonding layer~~ formed on a copper surface, the bonding layer comprising an alloy of:

(a) copper;

(b) tin; and

(c) at least one ~~type of~~ metal (third metal) selected from the group consisting of: silver, zinc, aluminum, titanium, bismuth, chromium, iron, cobalt, nickel, palladium, gold, and platinum,

wherein the copper is contained in an amount of 1 to 50 atom %, the tin is contained in an amount of 20 to 98 atom %, and the third metal is contained in an amount of 1 to 50 atom %, and

the bonding layer has a thickness of not less than 0.001 μm and not more than 1 μm , and

wherein the bonding layer is useful for an adhesive layer to resin.

2. (Original) The bonding layer according to claim 1,
wherein the copper surface is smooth.

3. (Original) The bonding layer according to claim 1,
wherein the copper surface is rough.

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4. (Original) The bonding layer according to claim 1,
wherein the bonding layer contains the copper in an amount in a range of 5 to 45 atom %.
5. (Original) The bonding layer according to claim 4,
wherein the bonding layer contains the copper in an amount in a range of 10 to 40 atom %.
6. (Original) The bonding layer according to claim 1,
wherein the bonding layer contains the tin in an amount in a range of 30 to 90 atom %.
7. (Original) The bonding layer according to claim 6,
wherein the bonding layer contains the tin in an amount in a range of 40 to 80 atom %.
8. (Original) The bonding layer according to claim 1,
wherein the bonding layer contains the third metal in an amount in a range of 2 to 45 atom %.
9. (Original) The bonding layer according to claim 8,
wherein the bonding layer contains the third metal in an amount in a range of 3 to 40 atom %.
10. (Original) The bonding layer according to claim 1,

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wherein the bonding layer has a thickness in a range of 0.001 to 0.5 μm .

11. (Original) The bonding layer according to claim 10,
wherein the bonding layer has a thickness in a range of 0.001 to 0.1 μm .